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IC PACKAGE STRUCTURE

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[There are no amendments to this patent.]

Claims

1. IC package structure characterized in that it has a first IC package, a first connecting terminal provided on a first surface of this first IC package and connected to a first electronic component, as well as a second connecting terminal provided on a second surface opposite from the first surface of the aforementioned first IC package and connected to a second electronic component.

2. The IC package structure described in Claim 1, characterized in that the aforementioned first electronic component is a second IC package and the aforementioned second electronic component is a printed circuit board.

3. The IC package structure described in Claim 1, characterized in that the aforementioned first and second electronic components are both printed circuit boards.

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